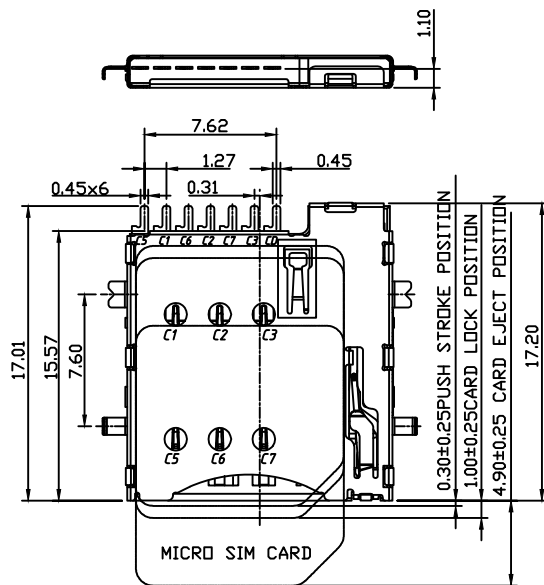
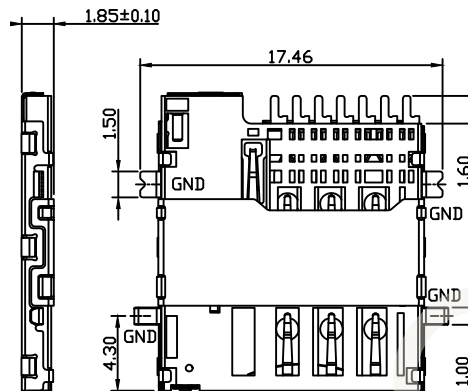
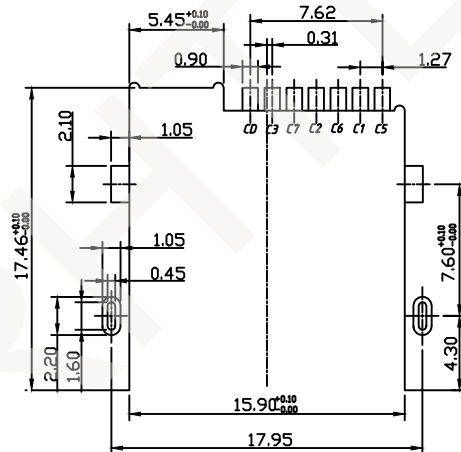


MICRO SIM CARD



RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE±0.05

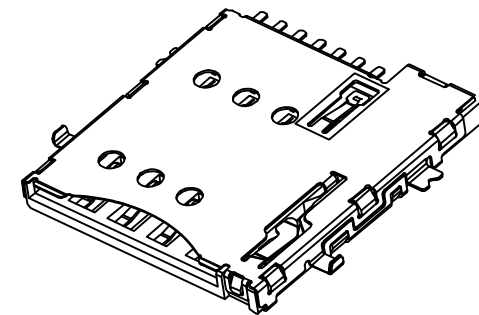


Material:

Insulator:High Temperature Thermoplastic,UlL94V-0,Black
Contact:Copper Alloy,Plated 30u" Ni Overall,Solder Area:Tin,Contact G/F
Shell:Stainless,30u" NiOverall Plated G/F Selective Contact Area.

Electrical:

Current Rating:0.5A max.
Voltage Rating:50V DC max.
Ambient Temperature Range:-20℃~+85℃
Storage Temperature Range:-40℃~+70℃
Ambient Humidity Range:95% R.H. Max.
Contact Resistance:100mΩ Max.
Insulation Resistance:1000MΩ Min./250V DC
Dielectric Withstanding Voltage:500V AC
Mating Cycles:5000 Insertions
Temperature:260℃±5℃



SIM Pin Assignment	
Pin#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



NINGBO RHT ELECTRONIC CO.,LTD

UNITS:mm	SHEET SIZE: A4		SCALE:---
0~3	3~18	18~50	50~120
±0.12	±0.15	±0.3	±0.5

DRWN BY PAN
CHK'D BY FENG
APPR BY ZHAN

Micro SIM CONN;Reverse MID MOUNT
1.1mm,6Pin,with CD Pin



RHTAYIM-097-7P-H1.35-R